

	CN No.	PCN03058	PCN Date	11/9/2022	Effective Date	4/25/2022	
Т	itle	BGA Tray Change from UBOT to Hwa Shu					

Type: Major

Carrier dimensions/configuration (tray) change (JEDEC)

Reason For Change

Using Manufacturing site preferred JEDEC tray Hwa Shu, primary medium for BGA packaging.

Affected Products

Part Number	Description	Medium
MR3A16ACMA35	512kx16 48-BGA 3.3V Industrial	Tray
MR3A16AMA35	512kx16 48-BGA 3.3V Commercial	Tray
MR4A08BCMA35	16Mb 2Mx8 48-BGA,3.3V Industrial	Tray
MR4A08BMA35	16Mb 2Mx8 48-BGA,3.3V Commercial	Tray
MR4A16BCMA35	16Mb 1Mx16 48-BGA, 3.3V Industrial	Tray
MR4A16BMA35	16Mb 1Mx16 48-BGA, 3.3V Commercial	Tray
MR5A16ACMA35	32Mb 2Mx16 48-BGA 3.3V Industrial	Tray
MR5A16AMA35	32Mb 2Mx16 48-BGA 3.3V Commercial	Tray
MR5A16AUMA45	32Mb 2Mx16 48-BGA 3.3V Auto Temp	Tray

Impact on Form, Fit, Function, Quality or Reliability

Impacts tray dimensions/configuration for packaging medium.

Proposed First Ship Date for Change:

Active in use

Key Material Differences

Hwa Shu Dimensions –(New) BGA TRAY 10 x 10mm 240 10 x 24 10mm-10x24 See attached below (JEDEC)

Ubot BGA Tray Dimensions – (old) 10x10 184 1.5x8x23 See attached below (JEDEC)

Product Identifier

Hwa Shu BGA Tray 10x10 mm

Supplier Qual Plan Schedule and Results

No Qualification required all Everspin requirements met.

Date Qualification Samples Are Available:

Samples are generally available now but please request your specific part number to your Everspin Sales contact.

Acceptance of Change (Customer)

Contact Information	Sample Information	Samples Available Now	
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Everspin Quality
Everspin Technologies
(480) 347-1111
bonnie.paro@everspin.com

Contact Everspin sales:

http://www.everspin.com/contact-us-everspin-technologies

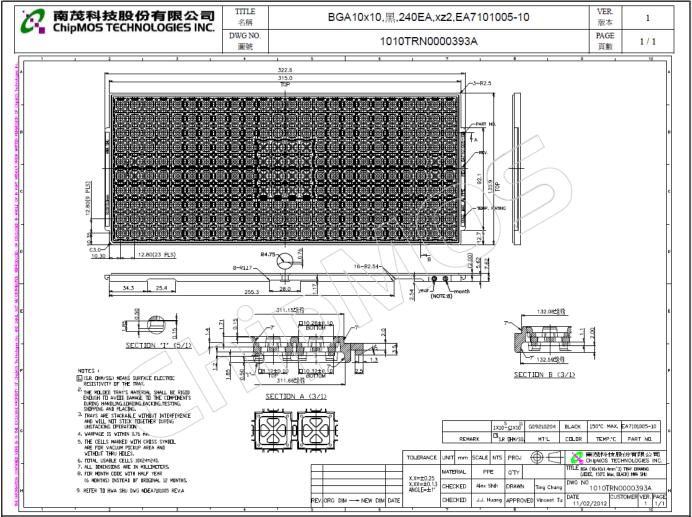
If using the on-line sample request, please refer to this PCN # to receive samples.

Originator						
<u>Date</u>	<u>Title</u>	<u>Name</u>				
11/9/2022	Senior Quality Engineer	Bonnie S. Paro Bon S. Paro				
Approval and Release						
<u>Date</u>	<u>Title</u>	<u>Name</u>				
11/9/2022	VP of Fab Ops & Quality	Mollan Rochet				
		Khaldoun Barakat Maklam Ambut				
<u>Date</u>	<u>Title</u>	<u>Name</u>				
Click here to enter a date.	VP of Backend Operations	14,~~~				
		Amit Shah				
<u>Date</u>	<u>Title</u>	<u>Name</u>				
11/9/2022	Sr. Director of Marketing	Joe O'Hare				



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Hwa Shu (NEW)



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UBOT (OLD)

